

N-CHANNEL 100V - 0.065 Ω - 4A SO-8 STripFET™ II POWER MOSFET

TYPE	V _{DSS}	R _{DS(on)}	ID
STS4NF100	100 V	<0.070 Ω	4 A

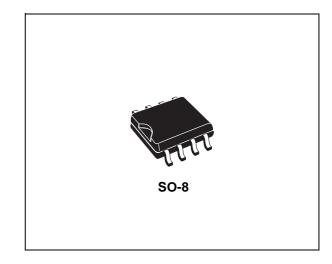
- TYPICAL $R_{DS}(on) = 0.065 \Omega$
- EXCEPTIONAL dv/dt CAPABILITY
- 100 % AVALANCHE TESTED
- APPLICATION ORIENTED CHARACTERIZATION

DESCRIPTION

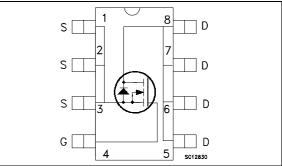
This MOSFET series realized with STMicroelectronics unique STripFET process has specifically been designed to minimize input capacitance and gate charge. It is therefore suitable as primary switch in advanced highefficiency, high-frequency isolated DC-DC converters for Telecom and Computer applications. It is also intended for any applications with low gate drive requirements.

APPLICATIONS

- HIGH-EFFICIENCY DC-DC CONVERTERS
- UPS AND MOTOR CONTROL



INTERNAL SCHEMATIC DIAGRAM



ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Parameter Value	
V _{DS}	Drain-source Voltage (V _{GS} = 0)	100	V
V _{DGR}	Drain-gate Voltage (R_{GS} = 20 k Ω)	100	V
V _{GS}	Gate- source Voltage	± 20	V
ID	Drain Current (continuos) at $T_C = 25^{\circ}C$ Drain Current (continuos) at $T_C = 100^{\circ}C$	4 2.5	A A
I _{DM} (●)	Drain Current (pulsed)	16	A
P _{tot}	Total Dissipation at $T_C = 25^{\circ}C$	2.5	W

(•) Pulse width limited by safe operating area.

July 2001

THERMAL DATA

T _j Therma	rmal Resistance Junction-ambient al Operating Junction-ambient e Temperature	Single Operatio	50 -55 to 150 -55 to 150	°C/W °C °C	
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 $(\ensuremath{^{\star}})$ Mounted on FR-4 board (t \leq 10 sec.)

ELECTRICAL CHARACTERISTICS ($T_{case} = 25 \text{ °C}$ unless otherwise specified)

OFF

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V _(BR) DSS	Drain-source Breakdown Voltage	$I_D = 250 \ \mu A, \ V_{GS} = 0$	100			V
I _{DSS}	Zero Gate Voltage Drain Current (V _{GS} = 0)	V_{DS} = Max Rating V_{DS} = Max Rating T _C = 125°C			1 10	μΑ μΑ
I _{GSS}	Gate-body Leakage Current (V _{DS} = 0)	$V_{GS} = \pm 20 V$			±100	nA

ON (*)

Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Unit
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}$	I _D = 250 μA	2	3	4	V
R _{DS(on)}	Static Drain-source On Resistance	V _{GS} = 10 V	I _D = 2 A		0.065	0.070	Ω

DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
g _{fs} (*)	Forward Transconductance	V_{DS} > $I_{D(on)}$ $xR_{DS(on)max}$ I_{D} = 2 A		10		S
C _{iss} C _{oss} C _{rss}	Input Capacitance Output Capacitance Reverse Transfer Capacitance	V _{DS} = 25V, f = 1 MHz, V _{GS} = 0		870 125 52		pF pF pF

ELECTRICAL CHARACTERISTICS (continued)

SWITCHING ON

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t _{d(on)} t _r	Turn-on Delay Time Rise Time			58 45		ns ns
Q _g Q _{gs} Q _{gd}	Total Gate Charge Gate-Source Charge Gate-Drain Charge	V _{DD} = 80V I _D = 4A V _{GS} =10V		30 6 10	41	nC nC nC

SWITCHING OFF

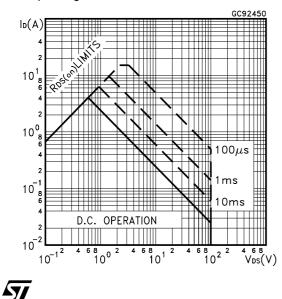
Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t _{d(off)} t _f	Turn-off Delay Time Fall Time			49 17		ns ns

SOURCE DRAIN DIODE

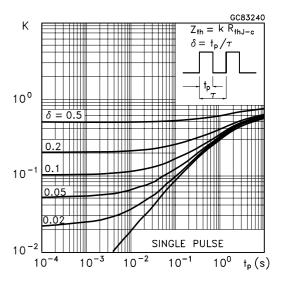
Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Unit
I _{SD} I _{SDM} (●)	Source-drain Current Source-drain Current (pulsed)					4 16	A A
V _{SD} (*)	Forward On Voltage	$I_{SD} = 4 A$	$V_{GS} = 0$			1.2	V
t _{rr} Q _{rr} I _{RRM}	Reverse Recovery Time Reverse Recovery Charge Reverse Recovery Current	$I_{SD} = 4 A$ $V_{DD} = 30 V$ (see test circu	di/dt = 100A/µs T _j = 150°C it, Figure 5)		100 375 7.5		ns nC A

(*)Pulsed: Pulse duration = 300 µs, duty cycle 1.5 %.
(•)Pulse width limited by safe operating area.

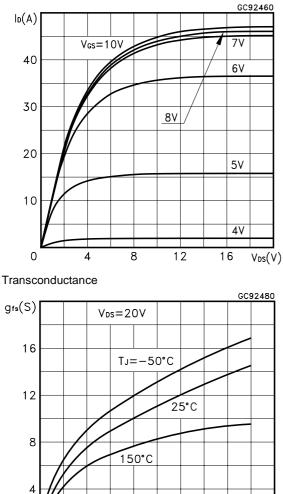
Safe Operating Area



Thermal Impedance

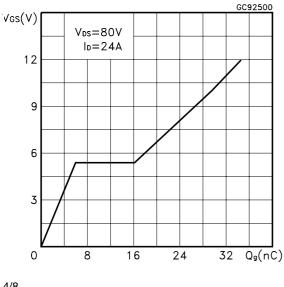


Output Characteristics

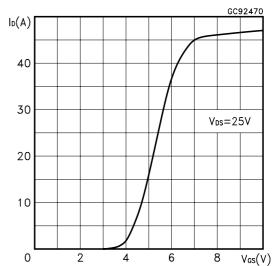


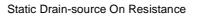


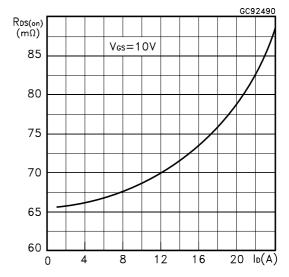
Gate Charge vs Gate-source Voltage



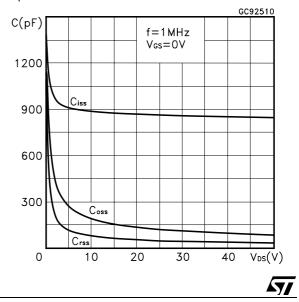
Transfer Characteristics

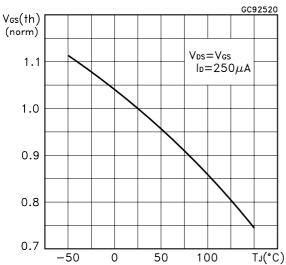






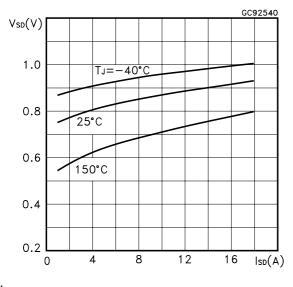
Capacitance Variations





Normalized Gate Threshold Voltage vs Temperature

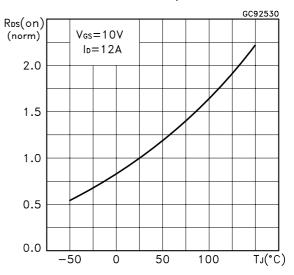
Source-drain Diode Forward Characteristics



Normalized on Resistance vs Temperature

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Fig. 1: Unclamped Inductive Load Test Circuit

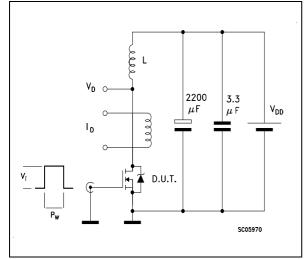
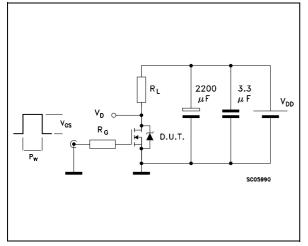
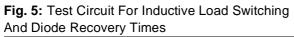


Fig. 3: Switching Times Test Circuits For Resistive Load





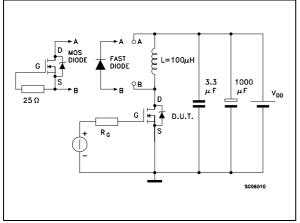


Fig. 2: Unclamped Inductive Waveform

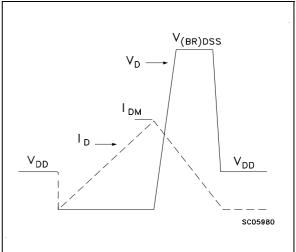
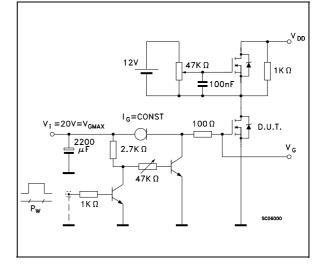


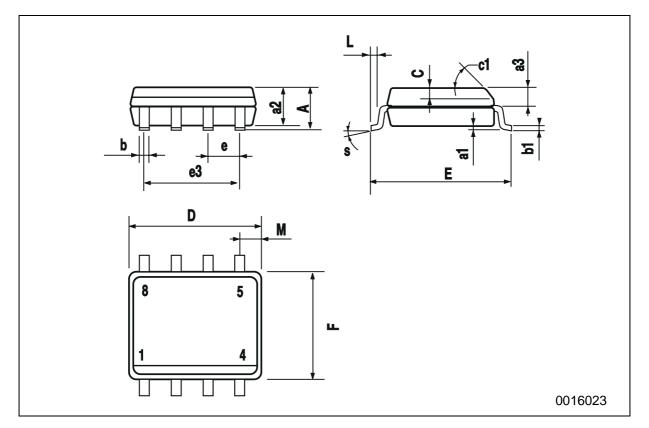
Fig. 4: Gate Charge test Circuit



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DIM.		mm			inch	
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
А			1.75			0.068
a1	0.1		0.25	0.003		0.009
a2			1.65			0.064
a3	0.65		0.85	0.025		0.033
b	0.35		0.48	0.013		0.018
b1	0.19		0.25	0.007		0.010
С	0.25		0.5	0.010		0.019
c1			45	(typ.)		
D	4.8		5.0	0.188		0.196
Е	5.8		6.2	0.228		0.244
е		1.27			0.050	
e3		3.81			0.150	
F	3.8		4.0	0.14		0.157
L	0.4		1.27	0.015		0.050
М			0.6			0.023
S			8 (r	max.)		





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